

TPS4141-Q1 Automotive 1200V Configurable Precision Resistor Divider With Integrated Switch

1 Features

- Qualified for automotive applications
 - AEC-Q100 grade 1: -40°C to 125°C ambient operating temperature
- Integrated high-voltage resistor divider
 - 30M Ω total resistance, precision matched divider
 - No exposed high-impedance nodes improves measurement integrity from board contaminants
- Integrated high-voltage disconnect switch
 - 1200V standoff voltage, uni-directional blocking
 - <1.5 μA leakage at $T_A = 105^{\circ}\text{C}$
- High accuracy divider and precision buffer amplifier
 - Buffered output for easy interfacing to analog-to-digital converters
 - Dynamically selectable gain settings to maximize accuracy across high-voltage sensing range
 - Typical gain error $\pm 0.15\%$
 - Maximum input offset error $\pm 220\text{mV}$
- Support for uni-directional and bi-directional voltage sensing up to $\pm 1200\text{V}$
- Dynamic switching between uni-directional and bi-directional voltage sensing operation
- Low supply current
 - 5mA ON state current
 - 5.5 μA OFF state current
- SOIC (DWQ-11) package
 - Creepage and clearance $\geq 8\text{mm}$ from high-voltage sensing pin to all other pins

2 Applications

- Hybrid, electric, and power train systems
- Battery management systems (BMS)
- Solar energy

3 Description

The TPS4141-Q1 is a high-voltage, precision matched resistor divider with an integrated programmable-gain amplifier. The TPS4141-Q1 also integrates a high-voltage switch to allow for connecting or disconnecting the high-voltage sense pin. The device is designed for automotive and industrial applications where accurate, high-voltage measurements are required.

The TPS4141-Q1 programmable-gain amplifier supports four divider ratios using DIV0 and DIV1 inputs. DIV0 and DIV1 can be set to fixed divider ratios and may also be changed dynamically while in operation. This allows for matching the amplifier output (AOUT) to the full-scale input voltage of the analog-to-digital signal chain, improving accuracy over the entire voltage sensing range of interest.

The TPS4141-Q1 supports uni-directional or bi-directional voltage measurement. Bi-directional voltage measurement is supported by supplying an external precision voltage reference from REF to HVGND. Switching between bi-directional and uni-directional voltage sensing during operation is possible using DIV0 and DIV1. Connecting REF to HVGND provides uni-directional voltage sensing only.

The TPS4141-Q1 integrates a high-voltage switch with a standoff voltage greater than 1200V from the high-voltage sense pin (HV) to ground (HVGND). The switch provides uni-directional current blocking from HV to HVGND when disconnected.

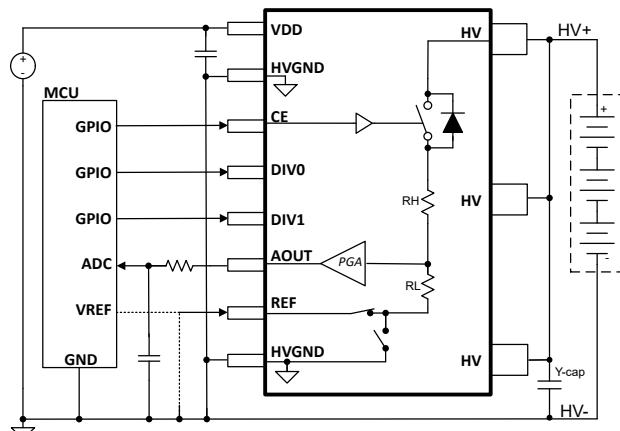
Package Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾
TPS4141-Q1 ⁽³⁾	DWQ (SOIC, 11)	10.30mm \times 10.30mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

(2) The package size (length \times width) is a nominal value and includes pins, where applicable.

(3) Product preview.



TPS4141-Q1 Simplified Application Schematic



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. ADVANCE INFORMATION for preproduction products; subject to change without notice.

Table of Contents

1 Features	1	6.4 Device Functional Modes.....	14
2 Applications	1	7 Application and Implementation	15
3 Description	1	7.1 Application Information.....	15
4 Pin Configuration and Functions	3	7.2 Typical Application.....	15
4.1 Pin Functions TPS4141-Q1.....	3	7.3 Power Supply Recommendations.....	18
5 Specifications	4	7.4 Layout.....	18
5.1 Absolute Maximum Ratings.....	4	8 Device and Documentation Support	20
5.2 ESD Ratings.....	4	8.1 Receiving Notification of Documentation Updates.....	20
5.3 Recommended Operating Conditions.....	4	8.2 Support Resources.....	20
5.4 Thermal Information.....	4	8.3 Trademarks.....	20
5.5 Power Ratings.....	5	8.4 Electrostatic Discharge Caution.....	20
5.6 Electrical Characteristics.....	5	8.5 Glossary.....	20
5.7 Switching Characteristics.....	7	9 Revision History	20
6 Detailed Description	8	10 Mechanical, Packaging, and Orderable Information	21
6.1 Overview.....	8	10.1 Tape and Reel Information.....	21
6.2 Functional Block Diagram.....	8		
6.3 Feature Description.....	9		

4 Pin Configuration and Functions

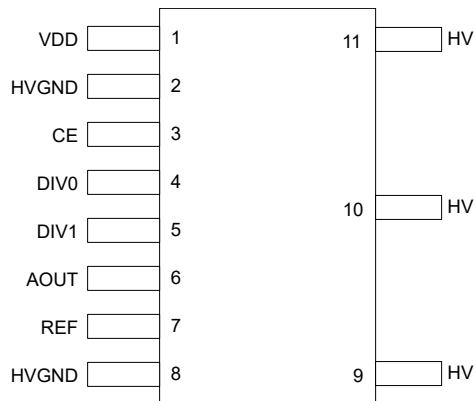


Figure 4-1. TPS4141-Q1 DWQ Package, 11-Pin SOIC-WB (Top View)

4.1 Pin Functions TPS4141-Q1

PIN NUMBER	PIN NAME	TYPE ⁽¹⁾	DESCRIPTION
1	VDD	P	Power supply
2	HVGND	GND	HV ground supply. Connect all HVGND pins to HV ground supply.
3	CE	I	Active high chip enable signal
4	DIV0	I	Trinary input for divider ratio selection
5	DIV1	I	Trinary input for divider ratio selection
6	AOUT	O	Amplifier output from HV resistor divider
7	REF	I	Reference for bottom of resistor divider, connect to external reference for bi-directional sensing or to HVGND.
8	HVGND	GND	HV ground supply. Connect all HVGND pins to HV ground return.
9	HV	I/O	High-voltage input. All HV pins must be connected in the application.
10			
11			

(1) P = power, I = input, O = output, GND = ground

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

PARAMETER		MIN	MAX	UNIT
V _{VDD}	Supply voltage ⁽²⁾	-0.3	20.7	V
V _{CE, DIV0, DIV1}	Chip enable and tri-state inputs voltage ⁽²⁾	-0.3	20.7	V
V _{AOUT, REF}	Resistor divider reference input and buffered resistor divider output ⁽²⁾	-0.3	6	V
V _{HV}	High voltage input ⁽²⁾	-1400	1400	V
T _J	Junction temperature	-40	150	°C
T _{stg}	Storage temperature	-65	150	°C

(1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.

(2) Voltage values are with respect to HVGND.

5.2 ESD Ratings

				VALUE	UNIT
HBM	Electrostatic discharge	Human body model (HBM), per AEC Q100-002 ⁽¹⁾ HBM ESD Classification Level 2	All pins	±2000	V
CDM	Electrostatic discharge	Charged device model (CDM), per AEC Q100-011 CDM ESD Classification Level C4	All pins	±750	V

(1) AEC Q100-002 indicates that HBM stressing must be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

PARAMETER		MIN	NOM	MAX	UNIT
V _{VDD}	Primary side supply voltage ⁽¹⁾	4.5	20	20	V
V _{CE, DIV0, DIV1}	Chip enable, divider selection input voltages ⁽¹⁾	0	20	20	V
V _{AOUT}	Buffered resistor divider output ⁽¹⁾	0	4.1	4.1	V
V _{REF}	Reference for bottom of resistor divider ⁽¹⁾	0	3.0	3.0	V
V _{HV}	Switch input voltage ⁽¹⁾	-1200	1200	1200	V
R _{AOUT}	External series resistance on AOUT ⁽²⁾	100	1000	1000	Ω
C _{AOUT}	External capacitance on AOUT ⁽²⁾	1	1000	1000	nF
T _A	Ambient operating temperature	-40	125	125	°C
T _J	Junction operating temperature	-40	150	150	°C

(1) Voltage values are with respect to HVGND.
 (2) External low pass RC filter from AOUT to HVGND.

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TPS4141-Q1	UNIT
		DWQ (SOIC)	
		11 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	70	°C/W
R _{θJB}	Junction-to-board thermal resistance	22	°C/W

5.4 Thermal Information (continued)

THERMAL METRIC ⁽¹⁾		TPS4141-Q1	UNIT
		DWQ (SOIC)	
		11 PINS	
$R_{\Theta JC(\text{top})}$	Junction-to-case (top) thermal resistance	26	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	14	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	21	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

5.5 Power Ratings

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
P_D	Maximum power dissipation, total (VDD and HV supplies)	$V_{VDD} = 5V$, $V_{CE} = 5V$ peak to peak, $V_{HV} = 1200V$ $f_{CE} = 1\text{Hz}$ square wave			110	mW
P_{D_VDD}	Maximum power dissipation (VDD supply)				50	mW
P_{D_HV}	Maximum power dissipation (HV supply)				60	mW

5.6 Electrical Characteristics

Unless otherwise noted, all minimum/maximum specifications are over recommended operating conditions. All typical values are measured at $T_J = 25^\circ\text{C}$, $V_{VDD} = 5V$, $V_{CE} = 5V$, $C_{AOUT} = 47\text{nF}$, $R_{AOUT} = 200\Omega$.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
PRECISION RESISTOR DIVIDER AND AMPLIFIER						
R_{TOTAL}	Resistance from HV to HVGND or HV to REF.		25	30	37	$\text{M}\Omega$
DIV_{NOM}	Nominal divide ratio	DIV1 = L, DIV0 = L	160			V/V
		DIV1 = L, DIV0 = H	320			V/V
		DIV1 = H, DIV0 = L	640			V/V
		DIV1 = H, DIV0 = H	1000			V/V
$GAIN_{\text{ERROR}}^{(1)(2)}$	DIV = 160V/V setting. Nominal gain = 1/DIV.	$T_J = 25^\circ\text{C}$	–0.15	0.15		%
		$–40^\circ\text{C} \leq T_J \leq 150^\circ\text{C}$	–0.25	0.25		%
	DIV = 320V/V setting. Nominal gain = 1/DIV.	$T_J = 25^\circ\text{C}$	–0.15	0.15		%
		$–40^\circ\text{C} \leq T_J \leq 150^\circ\text{C}$	–0.25	0.25		%
	DIV = 640V/V setting. Nominal gain = 1/DIV.	$T_J = 25^\circ\text{C}$	–0.15	0.15		%
		$–40^\circ\text{C} \leq T_J \leq 150^\circ\text{C}$	–0.25	0.25		%
	DIV = 1000V/V setting. Nominal gain = 1/DIV.	$T_J = 25^\circ\text{C}$	–0.15	0.15		%
		$–40^\circ\text{C} \leq T_J \leq 150^\circ\text{C}$	–0.25	0.25		%
$V_{\text{OFFSET_HV}}$	Measurement offset voltage referred to HV input.	$–40^\circ\text{C} \leq T_J \leq 150^\circ\text{C}$	–240	240		mV
CMR_{AIN}	Amplifier common mode input range		0	3.0		V
CMR_{AOUT}	Amplifier common mode output range		0	4.1		V

5.6 Electrical Characteristics (continued)

Unless otherwise noted, all minimum/maximum specifications are over recommended operating conditions. All typical values are measured at $T_J = 25^\circ\text{C}$, $V_{VDD} = 5\text{V}$, $V_{CE} = 5\text{V}$, $C_{AOUT} = 47\text{nF}$, $R_{AOUT} = 200\Omega$.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
BW _{HV_REF}	Measurement bandwidth - HV to AOUT, REF to AOUT	DIV = 160		7		kHz
		DIV = 320		14		kHz
		DIV = 640		30		kHz
		DIV = 1000		53		kHz
SUPPLY (VDD)						
V _{UVLO_R}	VDD undervoltage threshold rising	VDD rising	4	4.2	4.4	V
V _{UVLO_F}	VDD undervoltage threshold falling	VDD falling	3.9	4.1	4.3	V
V _{UVLO_HYS}	VDD undervoltage threshold hysteresis			160		mV
I _{VDD_ON}	VDD current, device powered on	T _J = 25°C		4		mA
		-40°C ≤ T _J ≤ 150°C		4	7.5	mA
I _{VDD_OFF}	VDD current, device powered off	V _{VDD} = 5V, V _{CE} = 0V, T _J = 25°C		4	7	µA
		V _{VDD} = 5V, V _{CE} = 0V, -40°C ≤ T _J ≤ 150°C			48	µA
		V _{VDD} = 20V, V _{CE} = 0V, T _J = 25°C		8	15	
		V _{VDD} = 20V, V _{CE} = 0V, -40°C ≤ T _J ≤ 150°C			60	µA
SWITCH CHARACTERISTICS						
I _{OFF}	Off leakage	CE = L, V _{HV} = 1200V, T _J = 25°C	0.02	0.15		µA
		CE = L, V _{HV} = 1200V, T _J = 85°C		0.5		
		CE = L, V _{HV} = 1200V, T _J = 105°C		1		
		CE = L, V _{HV} = 1200V, T _J = 125°C		5		
		CE = L, V _{HV} = 1200V, -40°C ≤ T _J ≤ 150°C		30		
BV _{VDSS}	Switch breakdown voltage.	I _{HV} = 8µA, T _J = 25°C CE = L	1270	1550		V
		I _{HV} = 30µA, -40°C ≤ T _J ≤ 150°C CE = L	1270	1550		V
C _{OSS}	HV capacitance	V _{HV} = 0V, f = 1MHz		2		pF
LOGIC-LEVEL INPUT (CE, DIV0, DIV1)						
V _{IL, CE}	Chip enable input logic low voltage		0.0	0.8		V
V _{IH, CE}	Chip enable input logic high voltage		2.4	20.0		V
V _{HYS, CE}	Chip enable input logic hysteresis			225		mV
V _{IL, DIVx}	DIV0/DIV1 input logic for low state			0.8		V
V _{IM, DIVx}	DIV0/DIV1 input logic for mid state		1.3	1.8		V
V _{IH, DIVx}	DIV0/DIV1 input logic for high state		2.4			V
V _{HYS, DIVx}	DIV0/DIV1 input logic hysteresis.			180		mV
I _{IL_CE}	Input logic low current	V _{CE} = 0V	-0.1	0.1		µA
		V _{CE} = 0.8V	1.3	2.3	4	µA
I _{IH_CE}	Input logic high current	V _{CE} = 5V	6.5	11	20	µA
		V _{CE} = 20V	6.6	12	22	µA

5.6 Electrical Characteristics (continued)

Unless otherwise noted, all minimum/maximum specifications are over recommended operating conditions. All typical values are measured at $T_J = 25^\circ\text{C}$, $V_{VDD} = 5\text{V}$, $V_{CE} = 5\text{V}$, $C_{AOUT} = 47\text{nF}$, $R_{AOUT} = 200\Omega$.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{IL_DIVx}	Input logic low current	$V_{DIVx} = 0\text{V}$	-23	-14	-8	μA
		$V_{DIVx} = 0.8\text{V}$	-11	-7	-4	μA
I_{IM_DIVx}	Input logic mid current	$V_{DIVx} = 1.3\text{V}$	-4	-2	-1	μA
		$V_{DIVx} = 1.8\text{V}$	1.3	2.4	5	μA
I_{IH_DIVx}	Input logic high current	$V_{DIVx} = 2.4\text{V}$	4	8	23	μA
		$V_{DIVx} = 5\text{V}$	9	17	32	μA
		$V_{DIVx} = 20\text{V}$	9	17	32	μA
R_{PD_CE}	Pull down resistance on CE		200	360	580	$\text{k}\Omega$
R_{PU_DIVx}	Pull up resistance on DIV0, DIV1		200	360	580	$\text{k}\Omega$
R_{PD_DIVx}	Pull down resistance on DIV0, DIV1		80	165	375	$\text{k}\Omega$

(1) Computed gain error (%) = $100 \times [DIV_{nom} (V_{AOUT,HV_max} - V_{AOUT,HV_min}) / (V_{HV_max} - V_{HV_min}) - 1]$

(2) Refer to [High Voltage Input Range](#) for V_{HV} input ranges supported for uni-directional and bi-directional operation.

5.7 Switching Characteristics

Unless otherwise noted, all minimum/maximum specifications are over recommended operating conditions. All typical values are measured at $T_J = 25^\circ\text{C}$, $V_{VDD} = 5\text{V}$, $V_{CE} = 5\text{V}$, $C_{AOUT} = 47\text{nF}$, $R_{AOUT} = 200\Omega$.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Switching Characteristics						
t_{ON}	CE rising to AOUT settles to 1% of steady state value.	$V_{HV} = 300\text{V}$, $DIV = 160$, $CE = L \rightarrow H$		240		μs
t_{OFF}	CE falling to AOUT pulled down to HVGND.	$V_{HV} = 300\text{V}$, $DIV = 160$, $CE = H \rightarrow L$ Measure when AOUT reaches 100mV referenced to HVGND.		190		μs
$t_{DIV_TOGGLE_STEP}$	Transition time from present DIV setting to next DIV setting to AOUT settles to % of steady state value.	$V_{HV} = 300\text{V}$, $V_{REF} = 0\text{V}$ or 2V . $DIV = 160 \rightarrow 320$, $DIV = 320 \rightarrow 160$ or $DIV = 320 \rightarrow 640$, $DIV = 640 \rightarrow 320$ or $DIV = 640 \rightarrow 1000$, $DIV = 1000 \rightarrow 640$. Settles within 0.25% of steady state value.		70		μs
t_{DIV_TOGGLE}	Transition time from lowest DIV setting to highest DIV setting to AOUT settles to % of steady state value.	$V_{HV} = 300\text{V}$, $V_{REF} = 0\text{V}$ or 2V . $DIV = 160 \rightarrow 1000$, $DIV = 1000 \rightarrow 160$. Settles within 0.25% of steady state value.		27		μs

6 Detailed Description

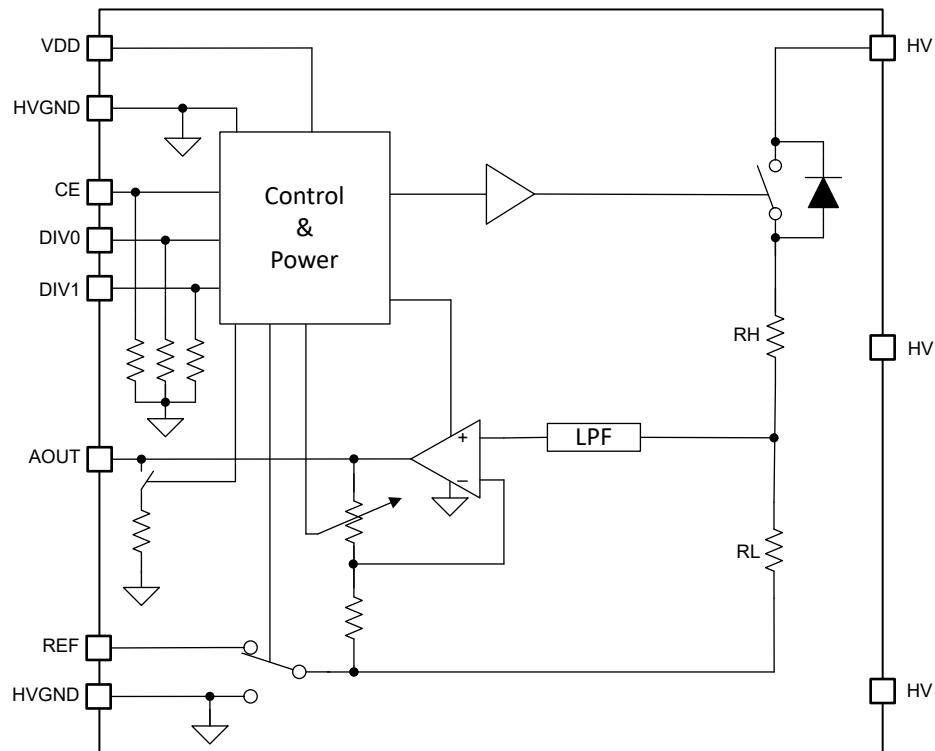
6.1 Overview

The TPS4141-Q1 is a high-voltage, precision matched resistor divider with an integrated programmable-gain amplifier. The TPS4141-Q1 also integrates a high-voltage switch to allow for connecting or disconnecting the high-voltage sense pin and provides uni-directional current blocking when disconnected. The device is designed for automotive and industrial applications where accurate, high-voltage measurements are required.

As seen in the *Functional Block Diagram* section, the TPS4141-Q1 integrates a high-voltage switch, two high-voltage resistors that form a precision matched divider, and a programmable gain amplifier (PGA). When the switch is enabled, a resistance (R_{TOTAL}) is presented between HV to HVGND or HV to REF.

The programmable gain amplifier has different gain settings. The gain settings, selectable via DIV0 and DIV1, in combination with the resistor divider, form an overall divide ratio (DIV) of the voltage present on the high-voltage pin (HV referenced to HVGND or REF). The resulting attenuated voltage is presented on AOUT relative to HVGND or REF. Four different divider ratios are possible. The divider ratios can be configured to be fixed via the DIV0 and DIV1 applied voltages or can be changed dynamically in the application.

6.2 Functional Block Diagram



6.3 Feature Description

6.3.1 Uni-directional Voltage Sensing

The TPS4141-Q1 can be configured for uni-directional voltage sensing as shown in [Figure 6-1](#). With uni-directional voltage sensing, REF is normally connected to HVGND. When configured in this manner, the TPS4141-Q1 measures only positive voltages present on HV referenced to HVGND, for example, 0V to 1200V. The output voltage of AOUT will always be positive with respect to HVGND.

DIV0 and DIV1 select the divide ratio (DIV) of the TPS4141-Q1 and can be changed dynamically in the application. This allows for optimization of the AOUT output swing over the complete voltage range present on HV, thereby improving overall accuracy.

The range of voltages that can be measured accurately depends on the divider ratio selected by DIV0 and DIV1. Refer to the [High Voltage Input Range](#) section for supported ranges.

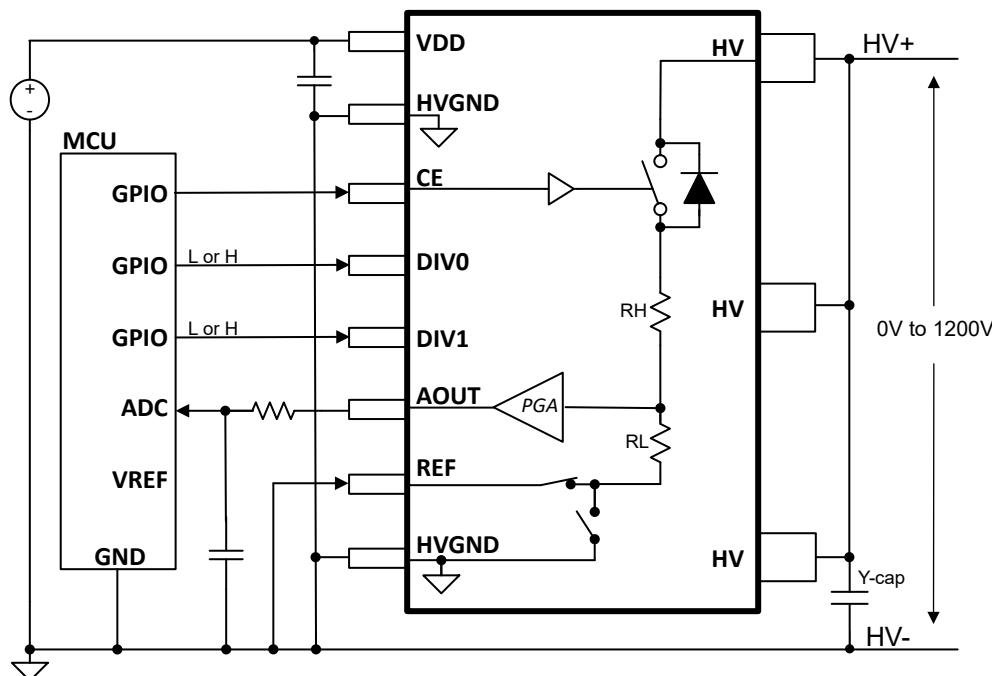


Figure 6-1. Uni-directional Voltage Sensing

6.3.2 Bi-directional Voltage Sensing

The TPS4141-Q1 can also be configured for bi-directional voltage sensing as shown in [Figure 6-2](#). With bi-directional voltage sensing, REF is connected to an external precision voltage reference to offset the output voltage swing of the TPS4141-Q1 amplifier. With bi-directional voltage sensing, the TPS4141-Q1 can measure both positive and negative voltages present on HV referenced to HVGND, for example –1200V to 1200V. The voltage output of AOUT will swing above and below the applied voltage reference, V_{REF} .

DIV0 and DIV1 select the divide ratio (DIV) of the TPS4141-Q1 and can be changed dynamically in the application. This allows for optimization of the AOUT output swing over the complete voltage range present on HV, thereby improving overall accuracy.

The range of voltages that can be measured accurately depends on the divider ratio selected by DIV0 and DIV1, and reference voltage applied to REF. Refer to the [High Voltage Input Range](#) section for supported ranges. Normally, the external reference voltage is chosen to allow for symmetry of allowable ranges that can be supported for positive and negative input voltages, however this is not required.

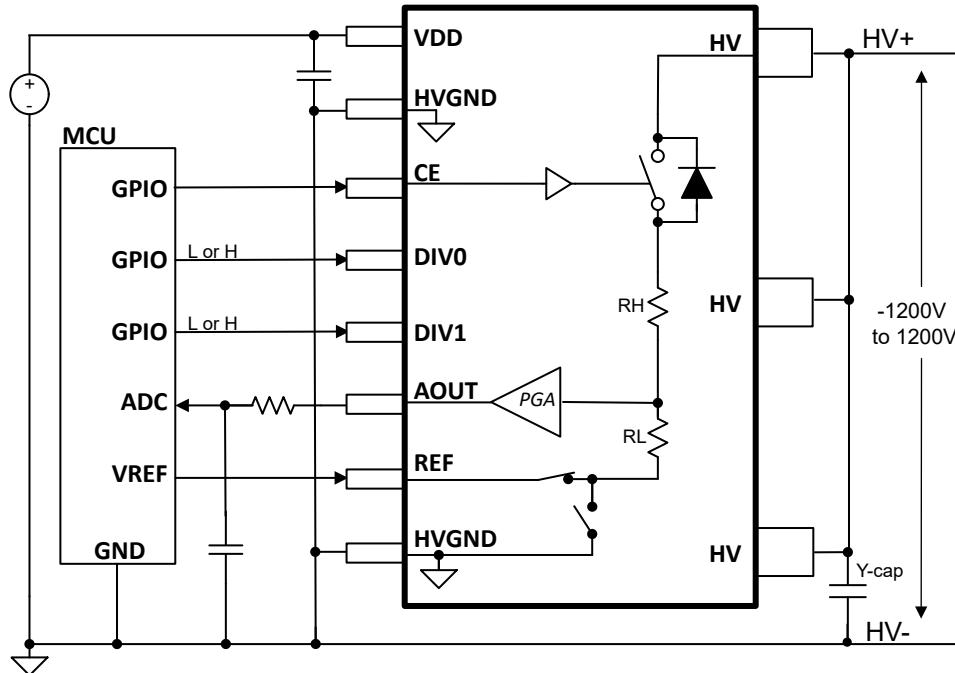


Figure 6-2. Bi-directional Voltage Sensing

6.3.3 Bi-directional and Uni-directional Voltage Sensing

The TPS4141-Q1 can also dynamically switch between uni-directional and bi-directional voltage sensing. REF is connected to an external precision voltage reference, identical to the bi-directional configuration.

DIV0 and DIV1 pins are trinary inputs in that they can detect a logic low or high, as well as a Hi-Z condition present on their respective pins. The states of the DIV0 and DIV1 pins not only select the divide ratio (DIV), but also configure the device for bi-directional or uni-directional voltage sensing. When in bi-directional operation, the external reference voltage present on the REF pin is used and the TPS4141-Q1 can measure both positive and negative voltages present on HV referenced to HVGND, for example, –1200V to 1200V. The voltage output of AOUT will swing above and below the voltage present on the REF pin. When in uni-directional operation, the external reference voltage is bypassed internal to the device and HVGND is used as the reference and the TPS4141-Q1 can measure only positive voltages present on HV referenced to HVGND, for example, 0V to 1200V. The voltage output of AOUT will always be positive referenced to HVGND. These cases are shown in [Figure 6-3](#) and [Figure 6-4](#).

The range of voltages that can be measured accurately depends on the divider ratio selected by DIV0 and DIV1, and reference voltage applied to REF. Refer to the [High Voltage Input Range](#) section for supported ranges. Normally, the external reference voltage is chosen to allow for symmetry of allowable ranges that can be supported for positive and negative input voltages, however this is not required.

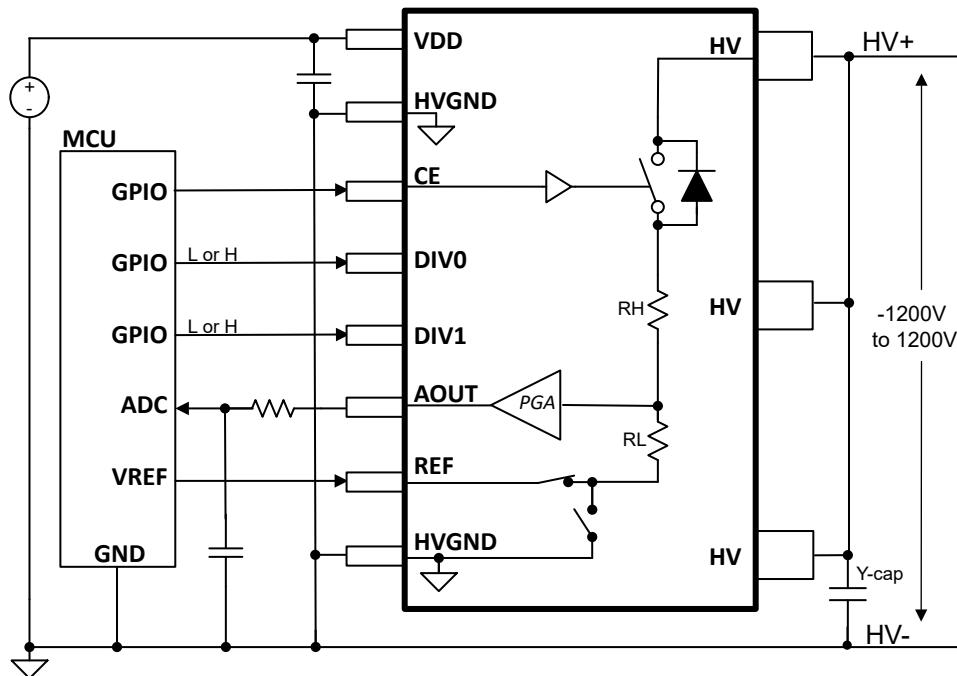


Figure 6-3. Bi-directional Voltage Sensing (DIV0 and DIV1 Set Logic Low or High)

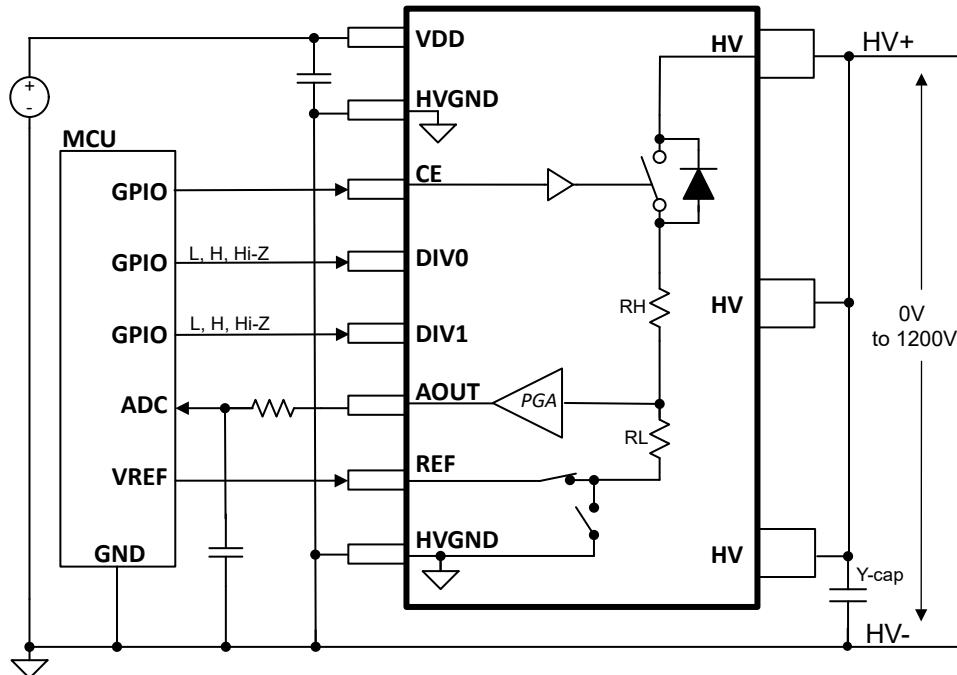


Figure 6-4. Bi-directional to Uni-directional Voltage Sensing (DIV0 and DIV1 Set Logic Low, High, or Hi-Z)

6.3.4 High Voltage Input Range

The input voltages on HV, V_{HV} , that can be sensed accurately by the TPS4141-Q1 depends on the DIV ratio selected and the REF voltage applied, V_{REF} . The common mode input and output voltage ranges of the integrated amplifier limit V_{HV} voltages that can be supported. Exceeding these ranges, cause the amplifier input or output to saturate.

The amplifier common mode output range, CMR_{AOUT} , limits the range of output voltages the amplifier can drive to AOUT. The voltage of AOUT is limited to $CMR_{AOUT(min)}$ to $CMR_{AOUT(max)}$ with respect to HVGND. Similarly, the amplifier common mode input range, CMR_{AIN} , limits the range of input voltages the amplifier can amplify. The input swing is limited to $CMR_{AIN(min)}$ to $CMR_{AIN(max)}$ with respect to HVGND.

The range of voltages that can be measured accurately depends on the divider ratio selected by DIV0 and DIV1 and the external reference voltage applied to REF. Figure 6-5 shows the typical characteristic of input ranges supported. For each DIV setting, a pair of curves is shown. The top curve corresponds to the upper bound of the V_{HV} voltage for the selected DIV setting and the bottom curve corresponds to the lower bound of the V_{HV} voltage. When the TPS4141-Q1 is configured for uni-directional measurements, REF is either connected to HVGND in the application or connected internally to HVGND via the DIV0 and DIV1 selections. In this case, $V_{REF} = 0V$.

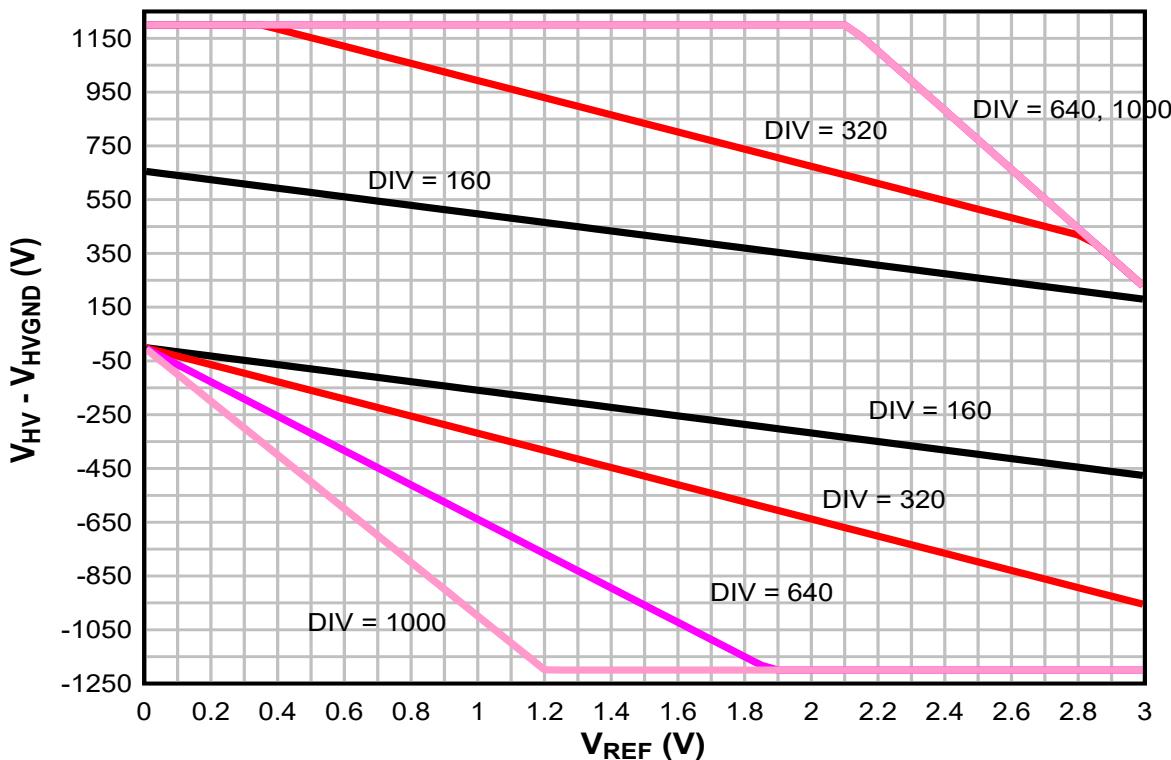


Figure 6-5. HV input ranges supported

6.3.5 Calculating the Output Voltage (V_{AOUT})

The TPS4141-Q1 measures the voltage on HV (V_{HV}) relative to the voltage on REF (V_{REF}). For bi-directional operation, REF is set to a positive voltage relative to HVGND in the application. The resulting voltage on AOUT (V_{AOUT}) swings above and below V_{REF} for positive and negative V_{HV} , respectively. For uni-directional operation, $V_{REF} = V_{HVGND} = 0V$ or is connected internally to HVGND automatically based on the DIV0 and DIV1 selections. Only positive V_{HV} voltages can be measured and resulting V_{AOUT} is positive with respect to HVGND.

Figure 6-6 shows the transfer function of the TPS4141-Q1 in uni-directional and bi-directional modes. Gain error causes an increase or decrease in the slope of the ideal transfer function curves.

Figure 6-7 shows the transfer function zoomed in of the TPS4141-Q1 in uni-directional and bi-directional modes. Offset error causes a shift up or down of the ideal transfer curves.

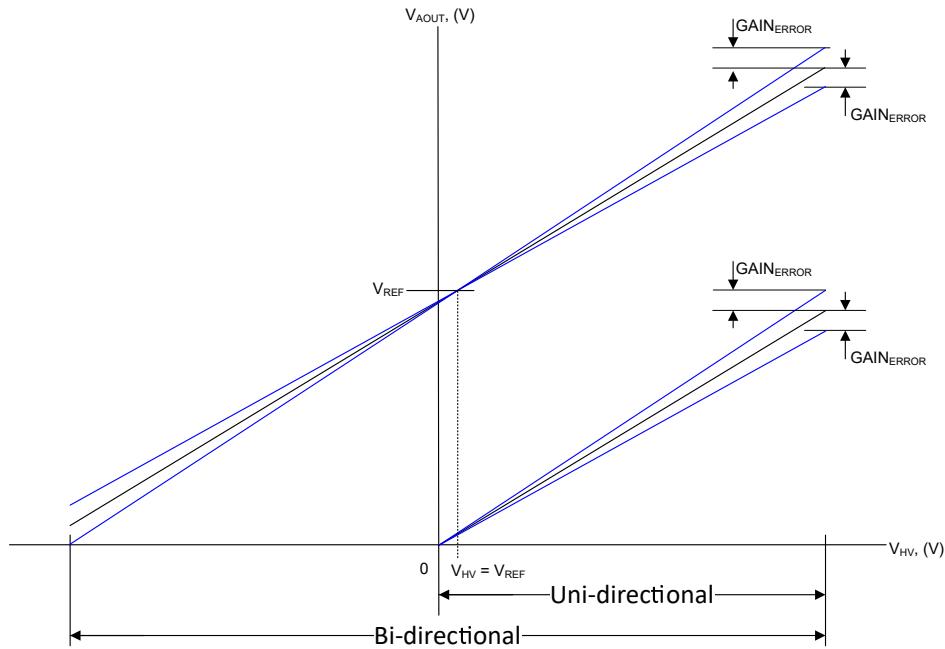


Figure 6-6. Transfer Function and Gain Error

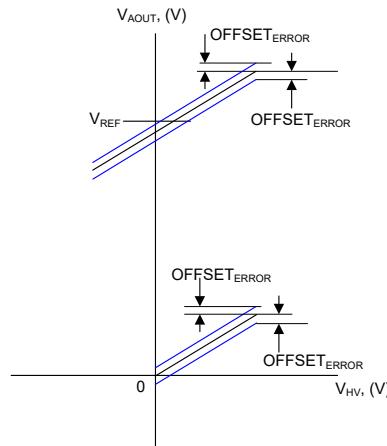


Figure 6-7. Transfer Function and Offset Error

There are several error sources that contribute to the overall measurement error of the system. These include, but are not limited, to the following:

- TPS4141-Q1 HV input offset error, V_{OFFSET_HV} .
- TPS4141-Q1 HV gain error percentage, $GAIN_{ERROR}$.
- Reference absolute accuracy percentage, REF_{ACC} .

Assuming no error sources, [Equation 1](#) can be used to estimate the AOUT voltage (V_{AOUT_IDEAL}):

$$V_{AOUT_IDEAL} = \frac{V_{HV} - V_{REF}}{DIV_{NOM}} + V_{REF} \quad (1)$$

When including the above listed error sources, [Equation 2](#) can be used to estimate the AOUT voltage (V_{AOUT}) for V_{REF} , V_{HV} , and DIV_{NOM} values of interest:

$$V_{AOUT} = \left[\frac{1 \pm \frac{GAIN_ERROR}{100}}{DIV_{NOM}} \right] \times \left[(V_{HV} \pm V_{OFFSET_HV}) - V_{REF} \times \left(1 \pm \frac{REF_ACC}{100} \right) \right] + V_{REF} \times \left(1 \pm \frac{REF_ACC}{100} \right) \quad (2)$$

Assuming no reference error, ($REF_ACC = 0$), [Equation 2](#) reduces to [Equation 3](#):

$$V_{AOUT} = \left[\frac{1 \pm \frac{GAIN_ERROR}{100}}{DIV_{NOM}} \right] \times \left(V_{HV} - V_{REF} \pm V_{OFFSET_HV} \right) + V_{REF} \quad (3)$$

Re-arranging [Equation 3](#), V_{HV} can be computed for a given V_{AOUT} using [Equation 4](#):

$$V_{HV} = \left[\frac{V_{AOUT} - V_{REF}}{\frac{GAIN_ERROR}{100}} \right] \times DIV_{NOM} + V_{REF} \pm V_{OFFSET_HV} \quad (4)$$

The relative percentage error to the ideal transfer curve, $\%ERROR_{REL}$, for a given V_{REF} can be found using [Equation 5](#):

$$\%ERROR_{REL} = 100\% \times \left[\frac{V_{AOUT} - V_{REF}}{V_{AOUT_IDEAL} - V_{REF}} - 1 \right] \quad (5)$$

Using [Equation 3](#) and [Equation 1](#), $\%ERROR_{REL}$ results in [Equation 6](#):

$$\%ERROR_{REL} = \pm 100\% \times \left[\left(1 + \frac{|GAIN_ERROR|}{100} \right) \times \left(1 + \frac{|V_{OFFSET_HV}|}{V_{HV} - V_{REF}} \right) - 1 \right] \quad (6)$$

6.4 Device Functional Modes

Table 6-1. Device Functional Modes

VDD	CE ⁽³⁾	V _{REF} ⁽³⁾	DIV1 ⁽³⁾	DIV0 ⁽³⁾	DIV ⁽³⁾	FUNCTION
Powered Up ⁽¹⁾	L	X	X	X	—	VDD current is in OFF state range. Resistor divider and AOUT buffer DISABLED.
	H	0 to 3.0V ⁽⁴⁾	L	L	160	Bi-directional voltage sensing. VDD current is in ON state range. Resistor divider and AOUT buffer ENABLED.
			L	H	320	
			H	L	640	
			H	H	1000	
Powered Up ⁽¹⁾	H	X	L	Hi-Z	160	Uni-directional voltage sensing. VDD current is in ON state range. Resistor divider and AOUT buffer ENABLED.
			H	Hi-Z	320	
			Hi-Z	H	640	
			Hi-Z	L or Hi-Z	1000	
Powered Down ⁽²⁾	X	X	X	X	—	VDD current is in OFF state range.

(1) $VDD \geq VDD$ undervoltage rising threshold.

(2) $VDD \leq VDD$ undervoltage falling threshold.

(3) X: do not care; L: logic low; H: logic high; Hi-Z: high-impedance.

(4) Refer to the [High Voltage Input Range](#) section for input ranges supported for a given V_{REF} .

7 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

7.1 Application Information

The TPS4141-Q1 is a high-voltage, precision matched resistor divider with an integrated programmable-gain amplifier. The TPS4141-Q1 also integrates a high-voltage switch to allow for connecting or disconnecting the high-voltage sense pin (HV) and provides uni-directional current blocking when disconnected. Intended applications include, but not limited to, are high-voltage monitoring in solar panels, electric vehicle (EV) chargers, EV battery management systems (BMS), and energy storage systems (ESS). The device is designed for automotive and industrial applications where accurate, high-voltage measurements are required.

The TPS4141-Q1 supports an input voltage range of 4.5V to 20V on the supply pin and a logic high of 2.4V to 20V on the CE, DIV0, and DIV1 pins. The TPS4141-Q1 supports up to 1200V uni-directional voltage sensing and up to $\pm 1200V$ bi-directional voltage sensing when an external reference voltage is supplied on REF.

7.2 Typical Application

Figure 7-1 shows a simplified circuit diagram using TPS4141-Q1 in a system for high voltage measurement. TPS4141-Q1 interfaces with the BQ79731-Q1 UIR sensor that contains an integrated delta-sigma ADC. In this example, both the TPS4141-Q1 and BQ79731-Q1 reside in the high voltage domain with their respective grounds connected to the battery ground, BAT- (HVGND = AVSS = BAT-).

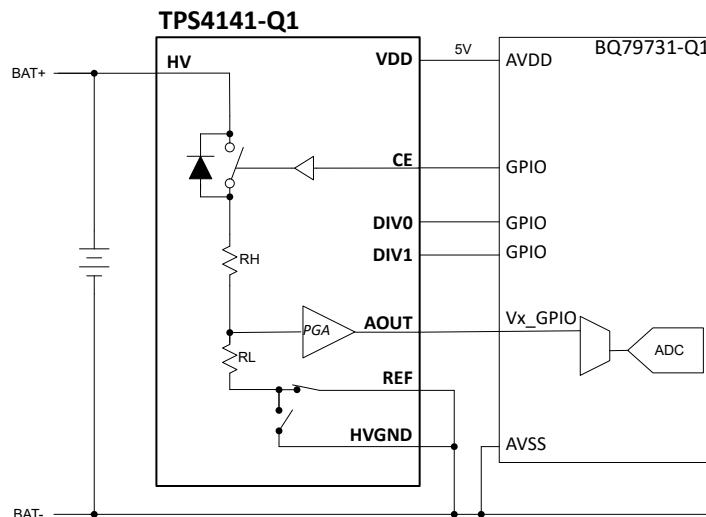


Figure 7-1. DC Bus Measurement With the TPS4141-Q1 and BQ79731-Q1

7.2.1 Design Requirements

Table 7-1 lists the Design Requirements for a typical high voltage measurement using a low voltage MCU to control the TPS4141-Q1. It assumes the MCU resides on the HVGND (ground of the high voltage domain).

Table 7-1. Design Requirements TPS4141-Q1 HV Measurement

PARAMETER	VALUE
V _{HV} voltage range	0V to 1000V
Supply (V _{VDD})	5V ±5%
ADC full scale input range	5V
ADC absolute measurement error	±1.5mV

7.2.2 Detailed Design Procedure

7.2.2.1 Divider Ratio Selection

In this example, the HV input range is positive with respect to BAT-, so the TPS4141-Q1 is configured for uni-directional operation as shown in Figure 7-2.

The divider ratio can be determined by referencing Figure 6-5. A divider ratio that maximizes the AOUT voltage range that is within the ADC full scale input range should be selected. With V_{REF} = 0V (REF = HVGND), the lowest divider ratio that can be used is DIV_{NOM} = 320V/V. Higher divider ratios are possible, but these reduce the AOUT voltage range with respect to the available ADC full scale input range.

DIV0 and DIV1 are used to select the nominal divider ratio. For applications that dynamically change the divider ratio in operation, these pins can be controlled by general purpose I/O of the MCU. For static divider ratio settings, DIV0 and DIV1 can be connected to the supply or ground thereby saving MCU general purpose I/O for other purposes. For this design, the divider ratio is assumed static, so DIV0 is connected to VDD and DIV1 is connected to HVGND.

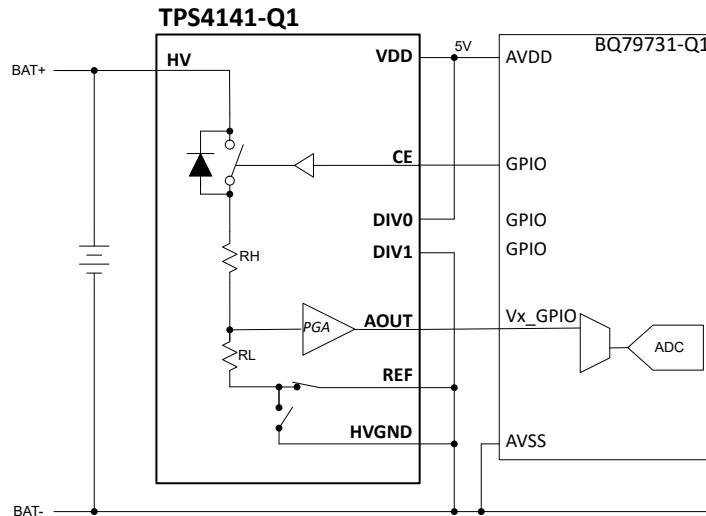


Figure 7-2. Uni-directional Measurement, DIV_{NOM} = 320V/V

If the application requires both positive and negative HV voltages to be measured with respect to BAT-, the TPS4141-Q1 can be configured for bi-directional operation as shown in Figure 7-3. An external 2.048V (V_{REF}) voltage reference is applied to REF which shifts the AOUT voltage to be centered around V_{REF}. DIV_{NOM} is increased to 640V/V to support a HV input range of -1000V to 1000V.

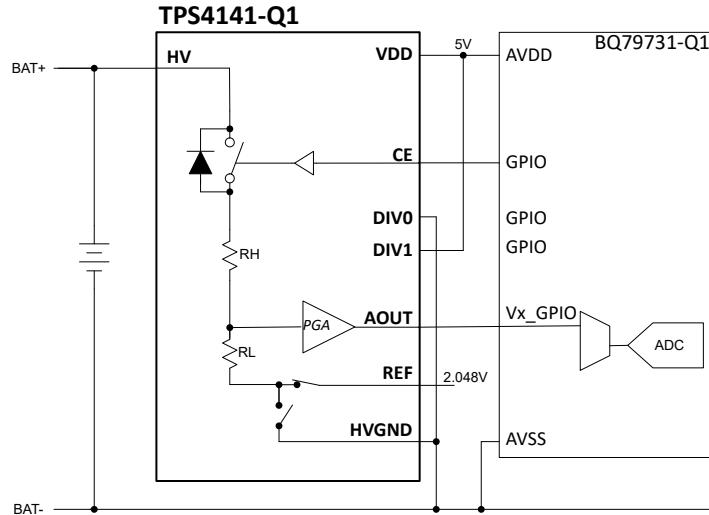


Figure 7-3. Bi-directional Measurement, $DIV_{NOM} = 640V/V$

7.2.2.2 Error Estimation

The following error sources are used to estimate the total measurement error:

- TPS4141-Q1 HV input offset error, V_{OFFSET_HV} , $\pm 240mV$.
- TPS4141-Q1 HV gain error, $GAIN_{ERROR}$, $\pm 0.25\%$.
- ADC absolute accuracy, ADC_{ACC} . For BQ79731-Q1, $\pm 1.5mV$.

For uni-directional operation, [Equation 3](#) is used to estimate the maximum and minimum AOUT voltage for a full scale range of $V_{HV} = 1000V$, $DIV_{NOM} = 320V/V$, and $V_{REF} = 0V$:

$$V_{AOUT} = (1 \pm 0.0025) \times \left[\frac{1000V \pm 0.24V}{320} \right] \quad (7)$$

$$V_{AOUT_MAX} = 3.13356V \quad V_{AOUT_MIN} = 3.11644V \quad (8)$$

The AOUT voltage with no error source contribution (V_{AOUT_IDEAL}) can be found using [Equation 1](#) with $V_{REF} = 0V$:

$$V_{AOUT_IDEAL} = \frac{1000V}{320} = 3.125V \quad (9)$$

Using V_{AOUT_MAX} , V_{AOUT_MIN} , and V_{AOUT_IDEAL} , the total full scale range percentage error is $\pm 0.274\%$. This may also be found by directly using [Equation 6](#):

$$\%ERROR_{REL} = \pm 100\% \times \left[\left(1 + \frac{0.25}{100} \right) \times \left(1 + \frac{0.24}{1000} \right) - 1 \right] = \pm 0.274\% \quad (10)$$

The ADC measurement error at full scale range is:

$$\%ERROR_{ADC} = \pm 100\% \times \left(\frac{1.5mV}{3.125V} \right) = \pm 0.048\% \quad (11)$$

Adding these error contributions leads to a total estimated error of $\pm 0.322\%$.

7.2.3 Application Curves

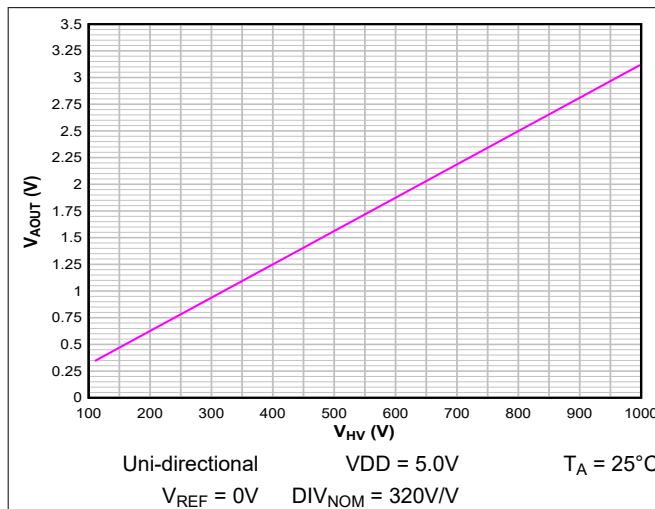


Figure 7-4. Transfer Function, Uni-directional Measurement

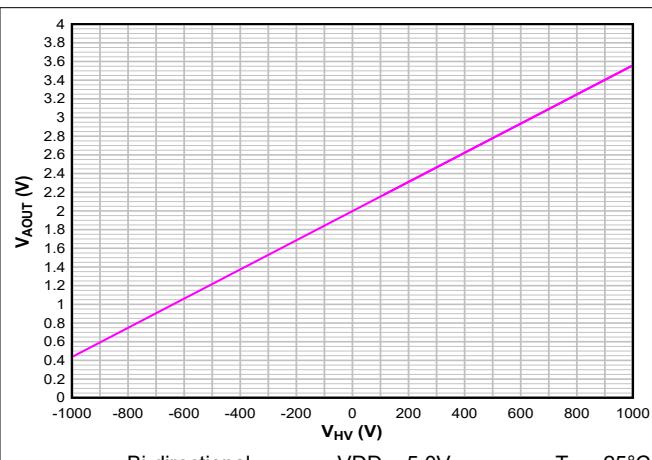


Figure 7-5. Transfer Function, Bi-directional Measurement

7.3 Power Supply Recommendations

To help ensure a reliable supply voltage, TI recommends that bypass capacitors be placed between VDD and HVGND. This capacitance consists of a 0.1 μ F bypass capacitor for high frequency decoupling in parallel with a 1 μ F capacitor for low frequency decoupling. Low-ESR and low-ESL capacitors must be connected close to the device as possible (<5mm).

7.4 Layout

7.4.1 Layout Guidelines

Component placement:

Decoupling capacitors intended for the filtering of high frequency signals must be placed as close as possible to the device pins. This action reduces the effect of trace inductance and achieves a cleaner signal.

EMI considerations:

To minimize EMI, capacitance placed between HV and HVGND will provide a low impedance path for any common mode noise generated by the device. In many applications, some form of capacitance may be present already and sufficient for this purpose.

IEC ESD considerations:

To improve robustness to meet IEC ESD contact discharge, capacitance can be placed from HV to HVGND. When doing so, this capacitance can serve a dual purpose to improve ESD and EMI performance. Typically, three to four series capacitors may be required to meet creepage and clearances, pending the system voltages applied.

High-voltage considerations:

To ensure high voltage spacing between HV and HVGND, avoid placing PCB or copper below the device. Proper placements and routing of signals to HV and all low voltage pins must be maintained to meet creepage and clearance standards.

Thermal considerations:

Proper PCB layout can help dissipate heat from the device to the PCB and minimize junction-to-board thermal impedance (θ_{JB}).

7.4.2 Layout Example

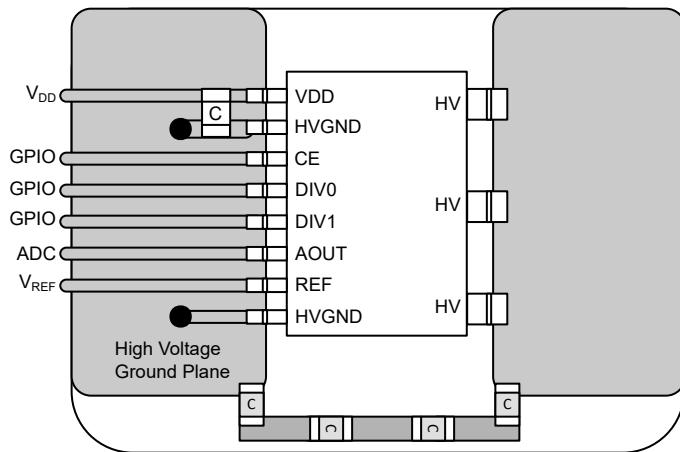


Figure 7-6. TPS4141-Q1 Example Layout

8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

8.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

8.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

8.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

9 Revision History

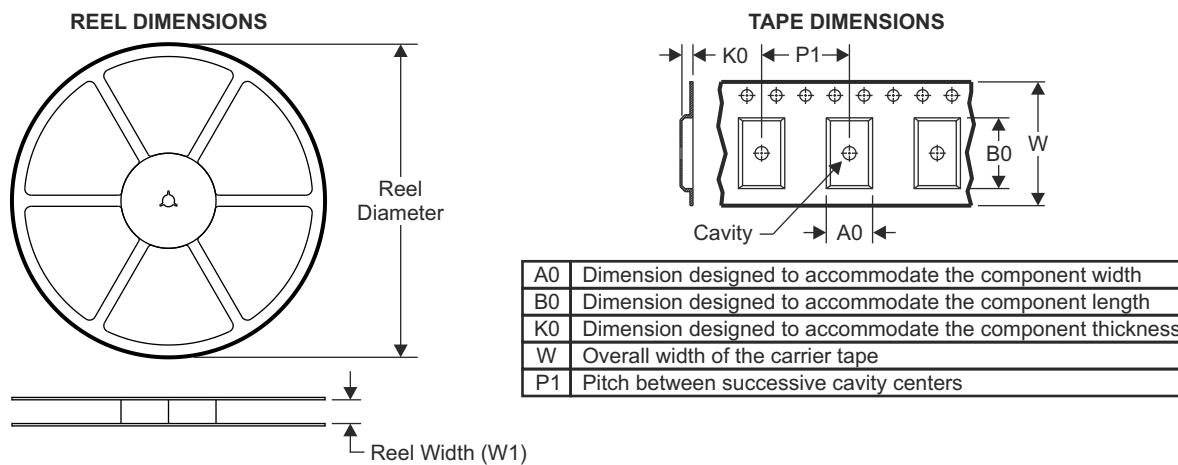
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision * (February 2025) to Revision A (May 2025)	Page
• Updated HV input ranges supported figure.....	11
• Added gain and offset error descriptions. Updated error equations.....	12
• Corrected VREF range.....	14
• Corrected VIH from 2.0V to 2.4V.....	15
• Updated error equations and calculation.....	17

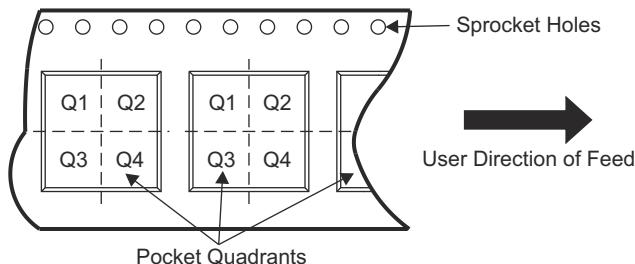
10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

10.1 Tape and Reel Information

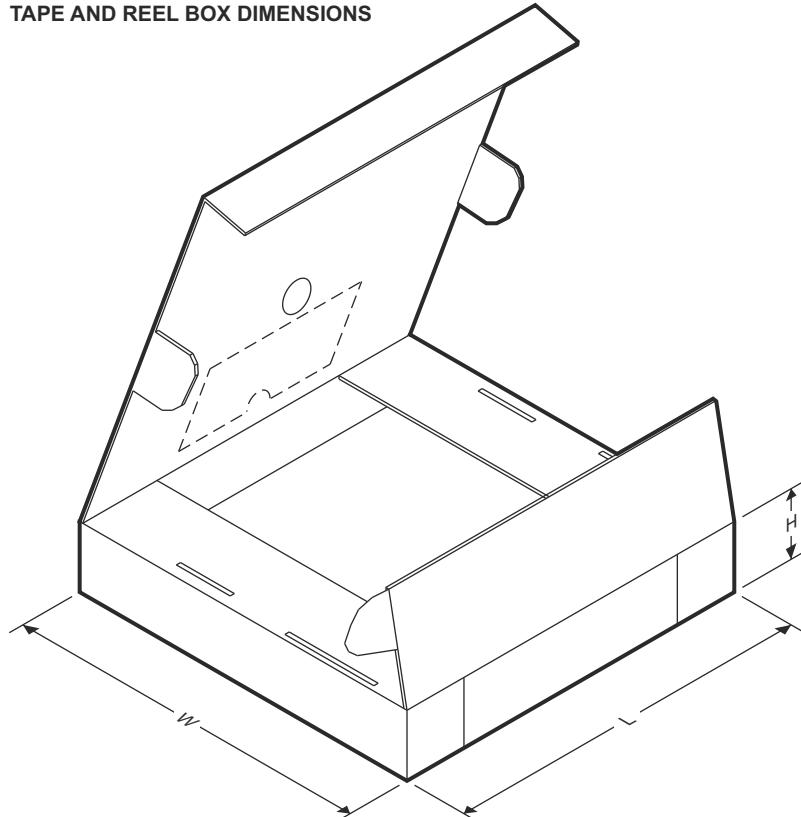


QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
XTPS4141QDWQRQ1	SOIC	DWQ	11	1000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
PTPS4141QDWQRQ1	SOIC	DWQ	11	1000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



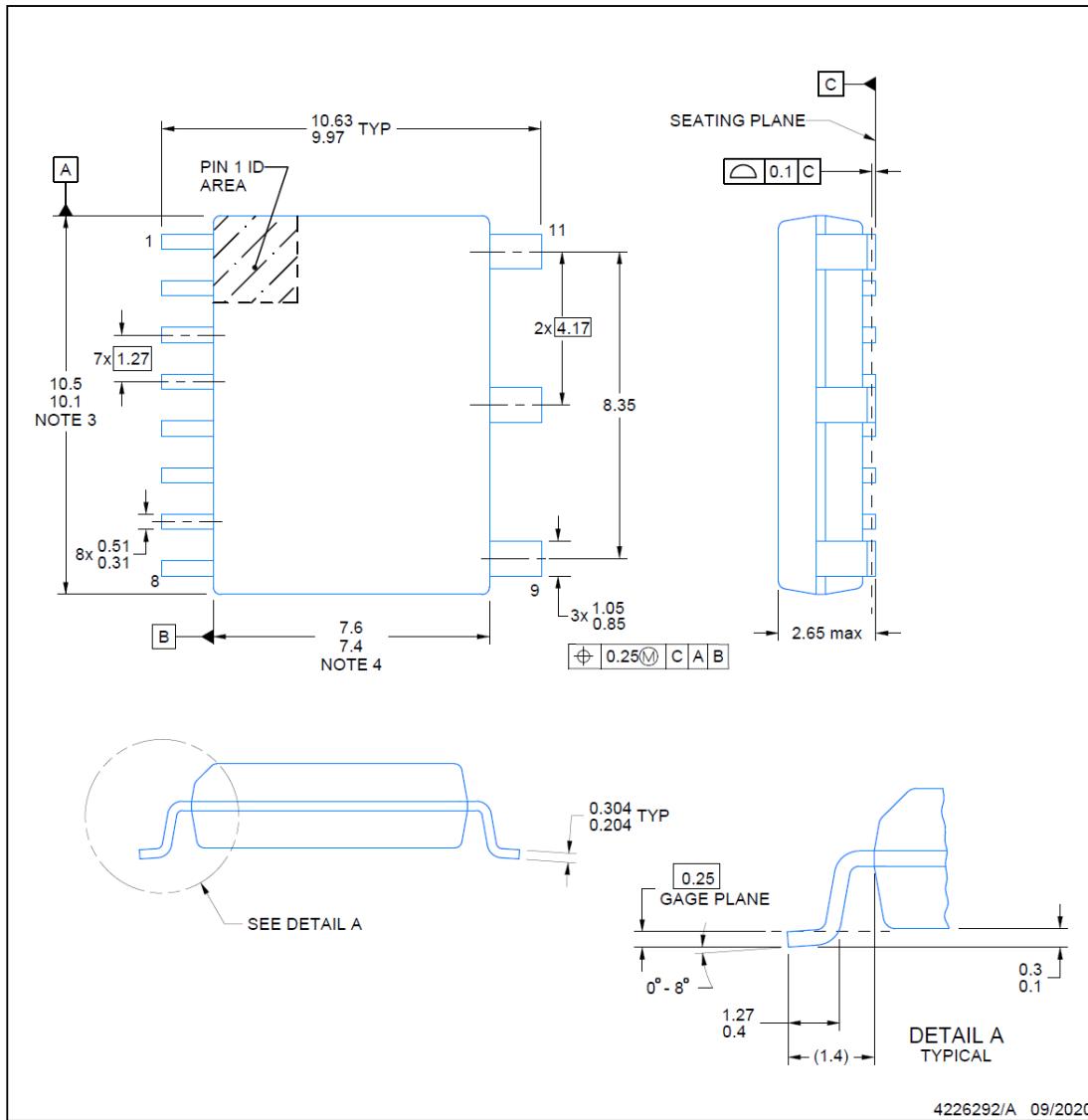
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
XTPS4141QDWQRQ1	SOIC	DWQ	11	1000	350.0	350.0	43.0
PTPS4141QDWQRQ1	SOIC	DWQ	11	1000	350.0	350.0	43.0

PACKAGE OUTLINE

DWQ0011A

SOIC - 2.65 mm max height

SMALL OUTLINE PACKAGE



4226292/A 09/2020

NOTES:

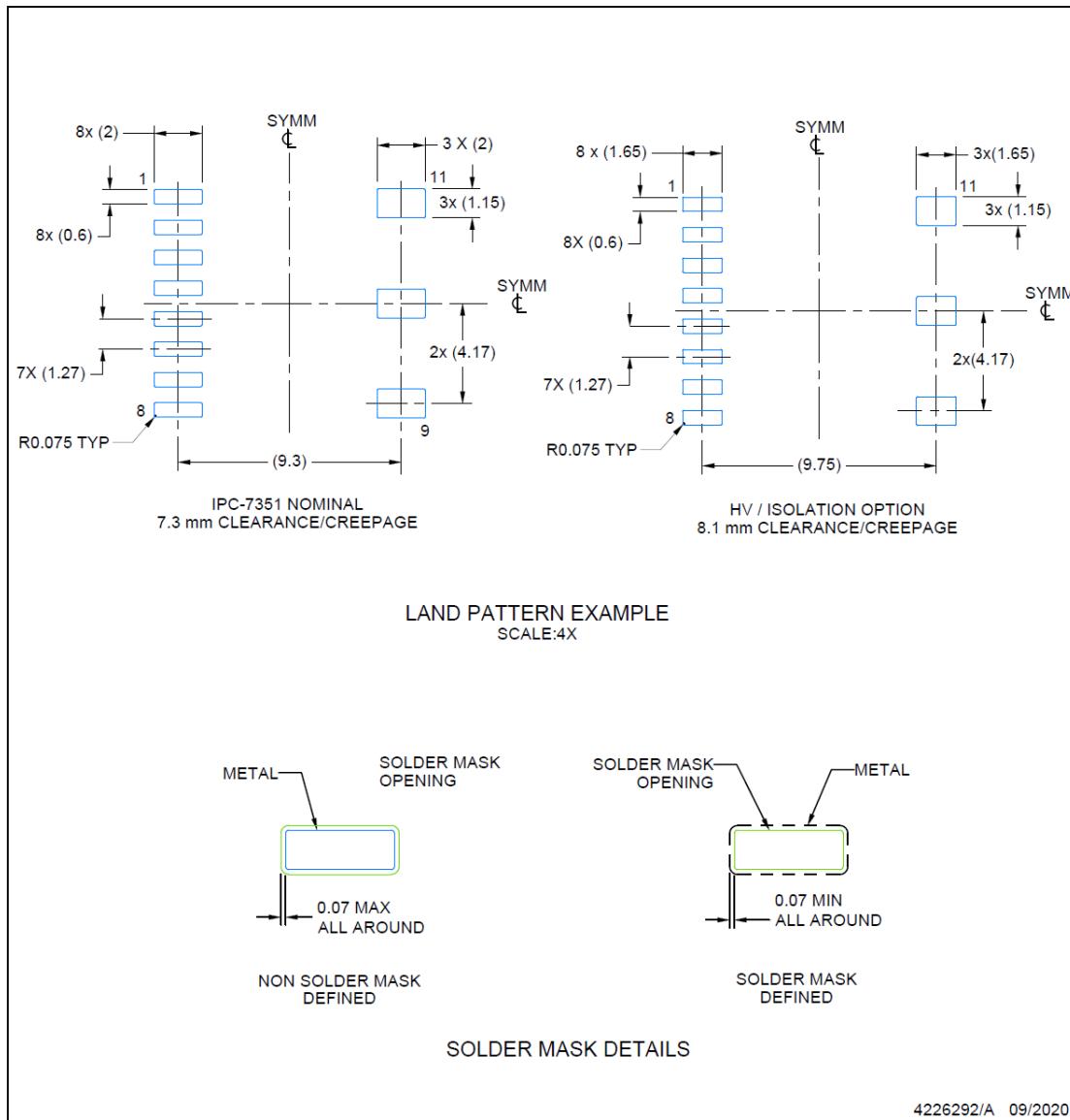
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

DWQ0011A

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

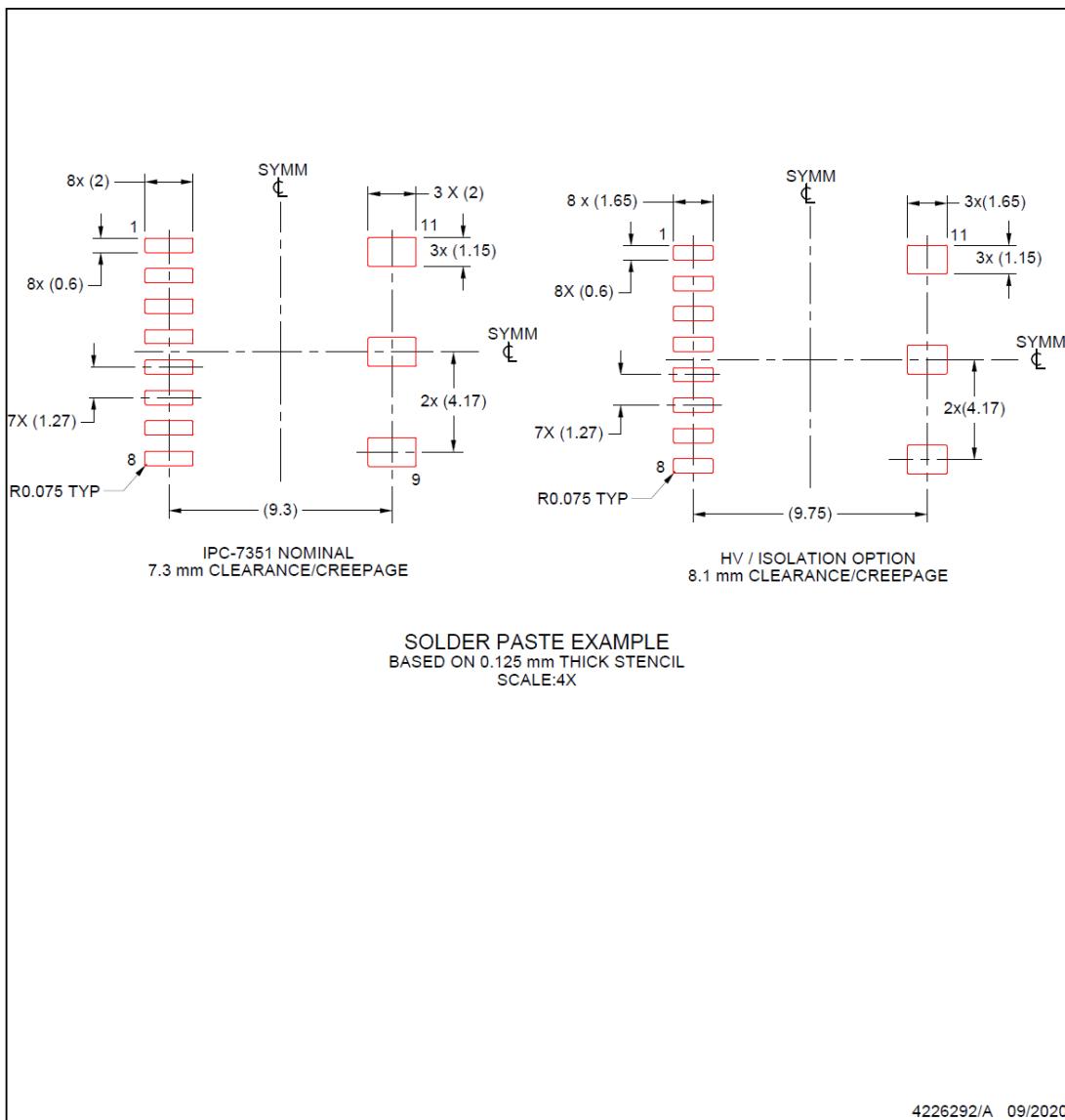
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DWQ0011A

SOIC - 2.65 mm max height

SOIG



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
PTPS4141QDWQRQ1	Active	Preproduction	SOIC (DWQ) 11	1000 LARGE T&R	-	Call TI	Call TI	-40 to 125	
XTPS4141QDWQRQ1	Active	Preproduction	SOIC (DWQ) 11	1000 LARGE T&R	-	Call TI	Call TI	-40 to 125	

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

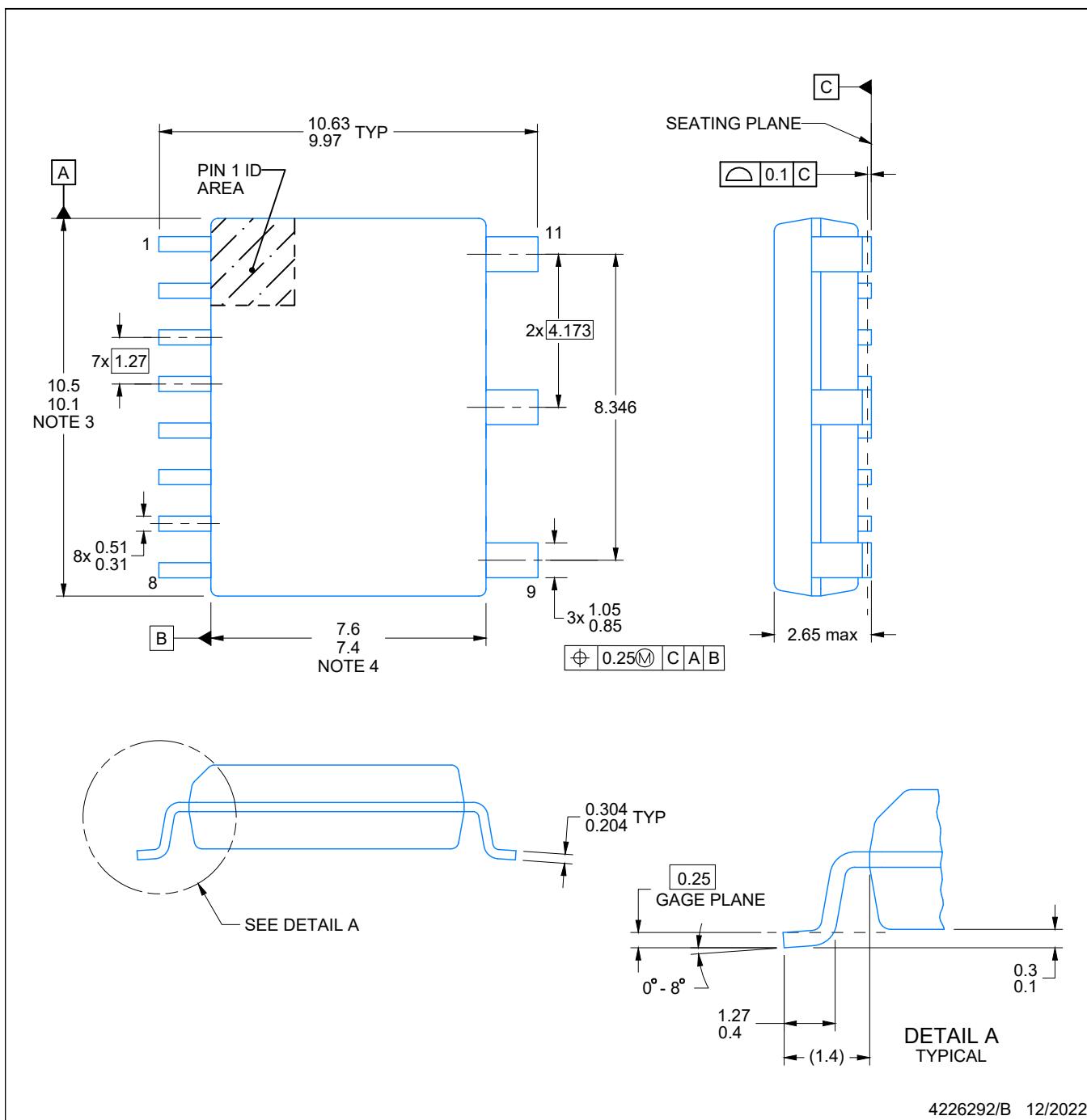
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE OUTLINE

DWQ0011A

SOIC - 2.65 mm max height

SMALL OUTLINE PACKAGE



4226292/B 12/2022

NOTES:

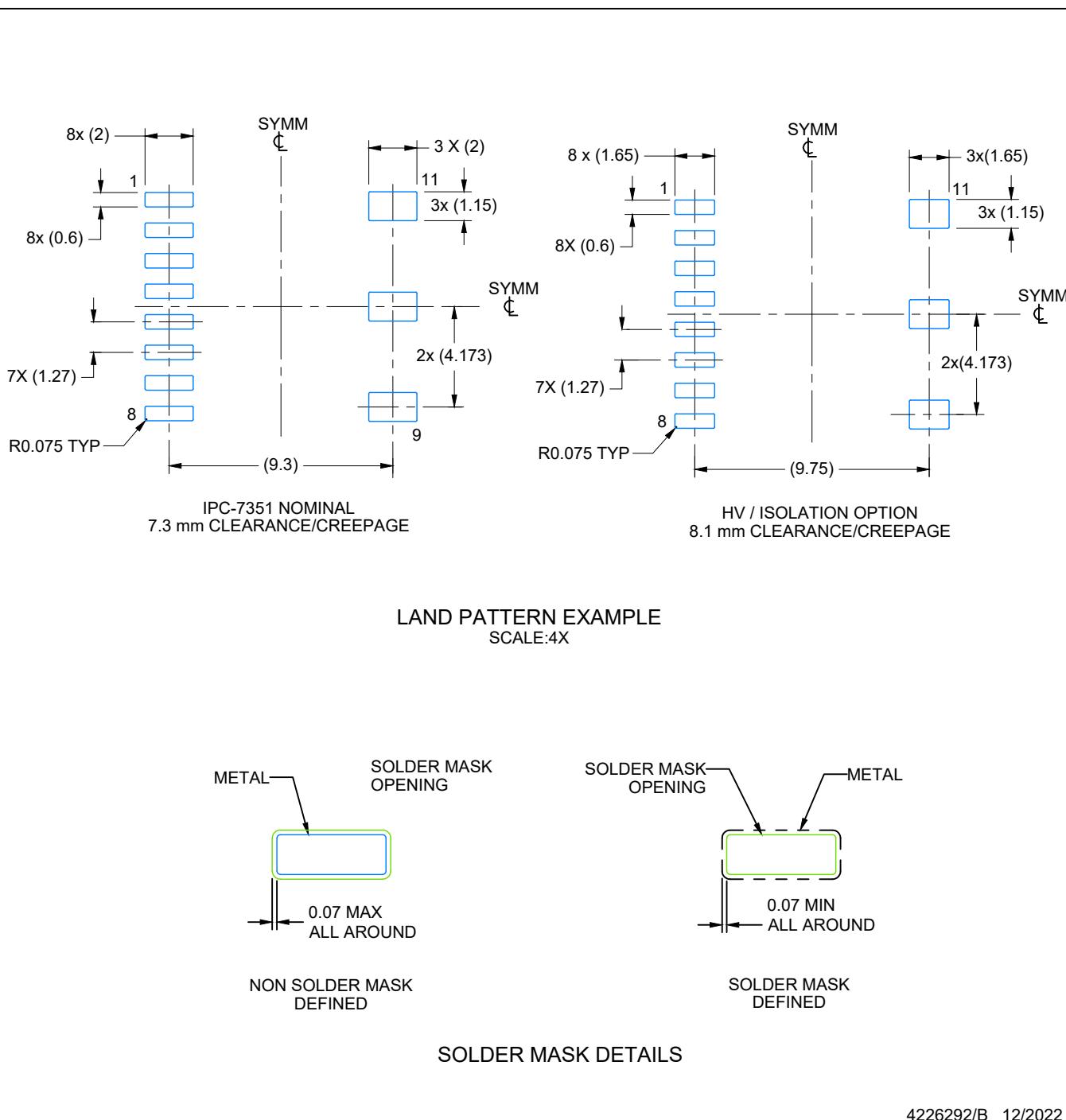
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

DWQ0011A

SOIC - 2.65 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

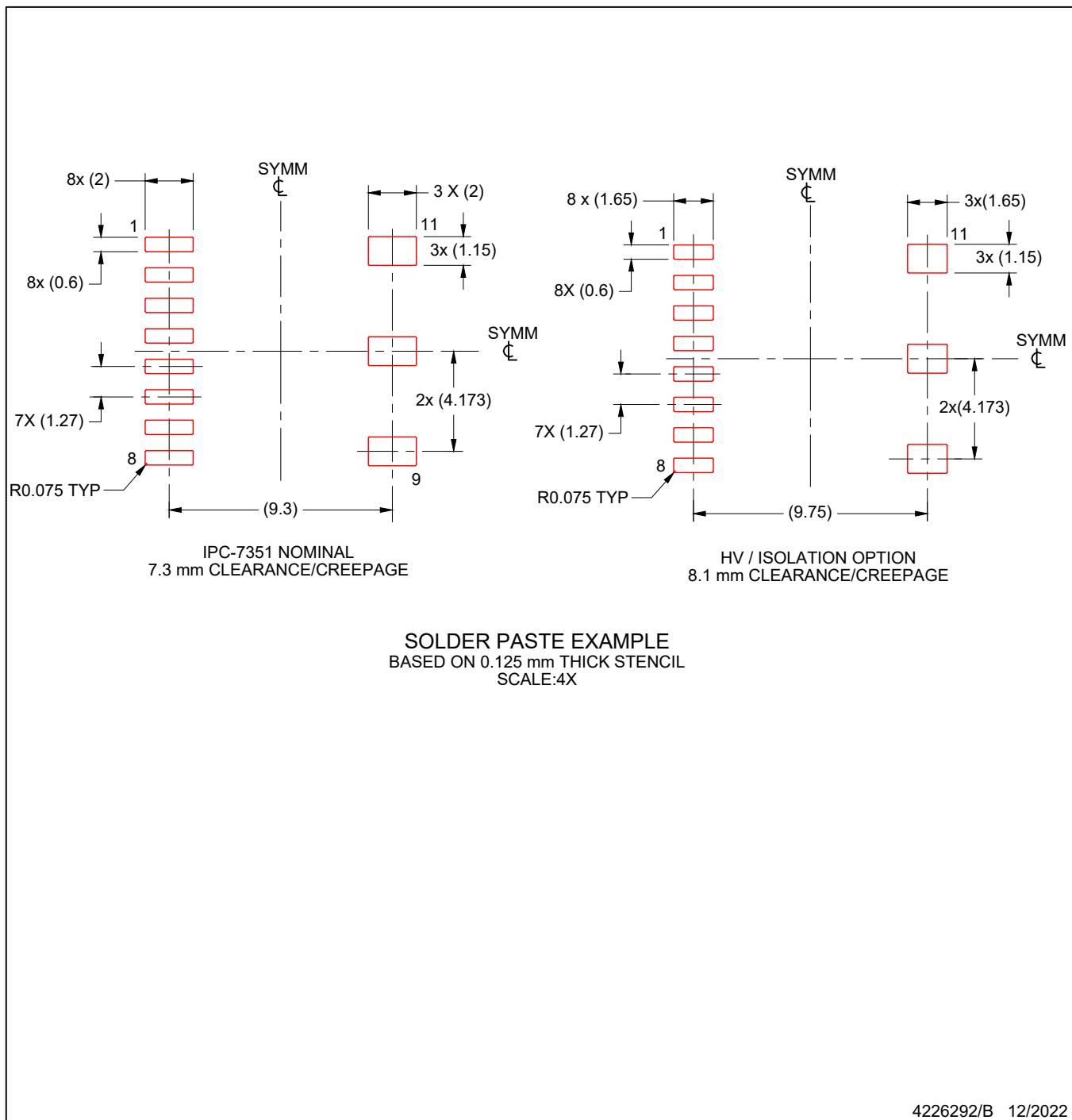
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DWQ0011A

SOIC - 2.65 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on [ti.com](#) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2026, Texas Instruments Incorporated

Last updated 10/2025